

**Description**

The SX100P04D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

**General Features**

$V_{DS} = -40V$   $I_D = -100A$

$R_{DS(ON)} < 5.8m\Omega$  @  $V_{GS} = -10V$

**Application**

Battery protection

Load switch

Uninterruptible power supply

**Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-100	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-66	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-300	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	400	mJ
$I_{AS}$	Avalanche Current	-50	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	52.1	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	62.5	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	1.8	°C/W

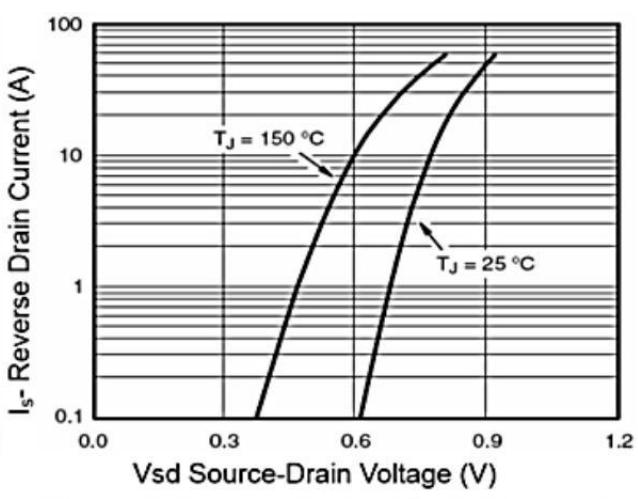
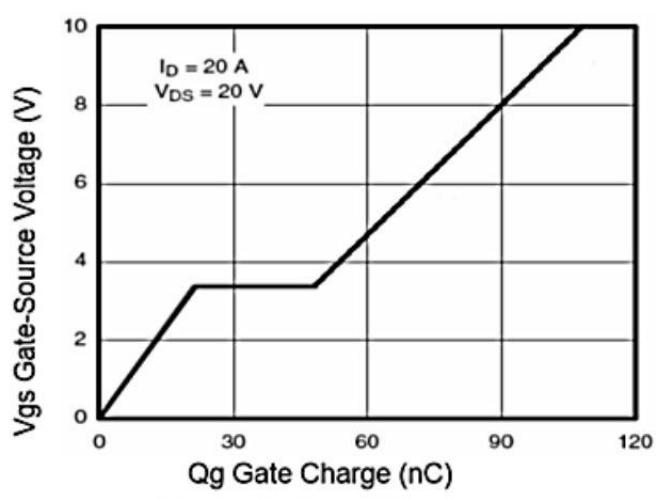
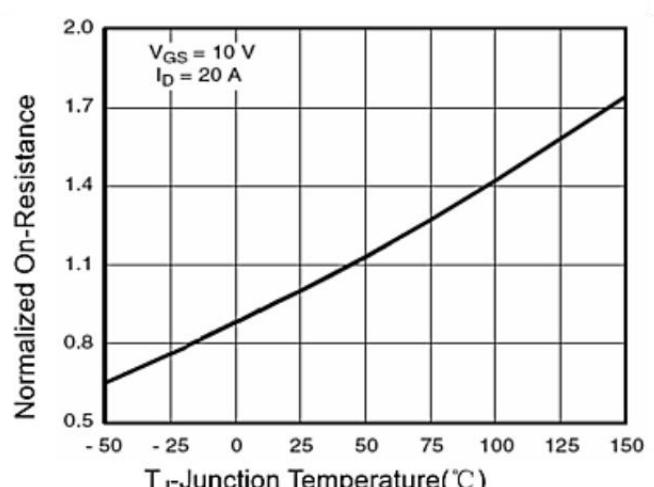
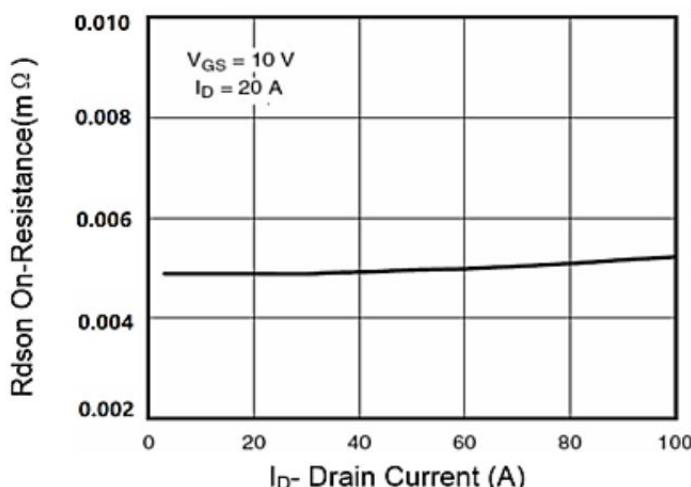
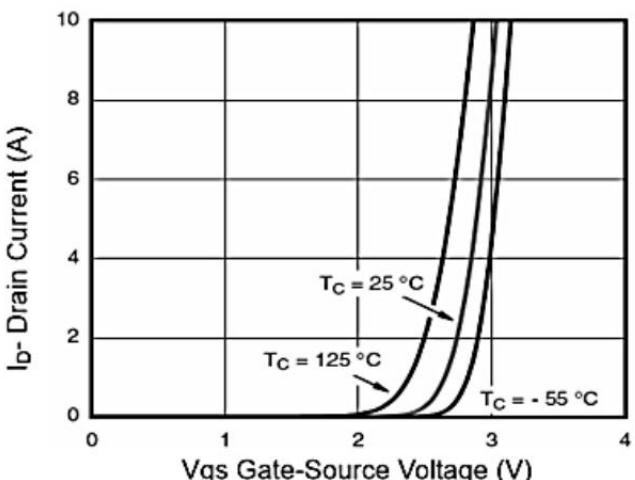
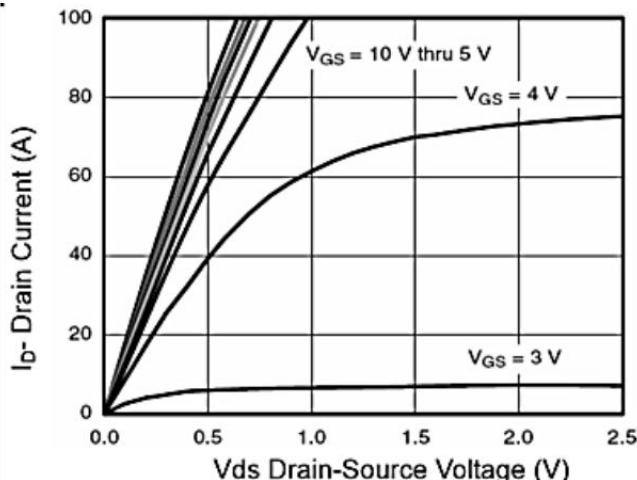
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-40	-44	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	-0.023	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-20\text{A}$	---	4.6	5.8	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-10\text{A}$	---	6.0	9.0	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.8	-2.5	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-40\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=-40\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-15\text{V}$ , $I_{\text{D}}=-12\text{A}$	---	50	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	7	14	$\Omega$
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-12\text{A}$	---	120	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	23	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	29	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=-20\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $R_g=3.0\Omega$ , $I_{\text{D}}=-12\text{A}$	---	18	---	ns
$T_r$	Rise Time		---	12	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	80	---	
$T_f$	Fall Time		---	20	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-20\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	7000	---	pF
$C_{\text{oss}}$	Output Capacitance		---	950	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	735	---	
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-100	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_{\text{S}}=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=-32\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $L=0.1\text{mH}$ , $I_{\text{AS}}=-50\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$ junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

## Typical Characteristics



### Typical Characteristics

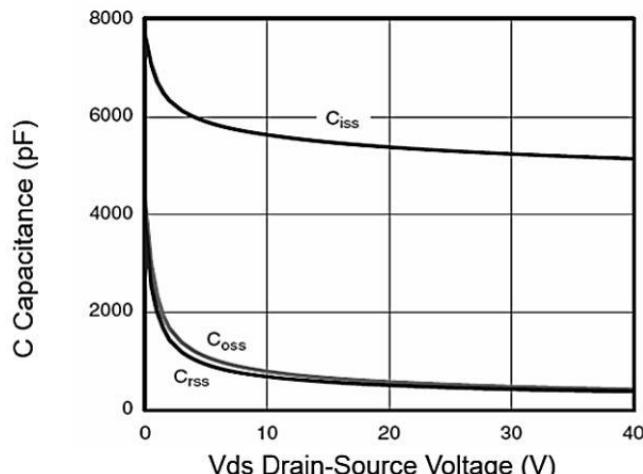


Figure 7 Capacitance vs Vds

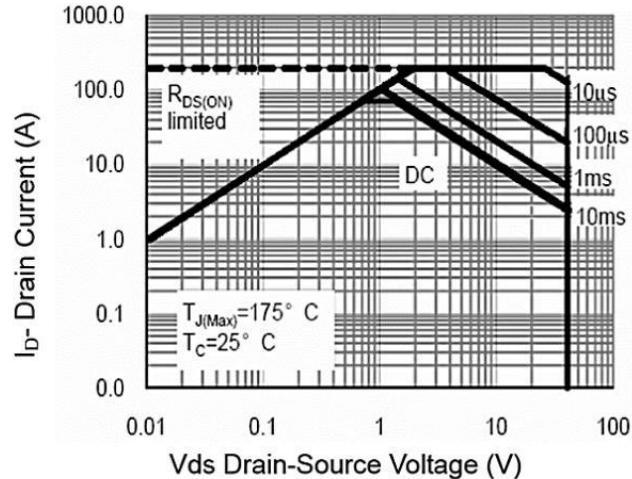


Figure 8 Safe Operation Area

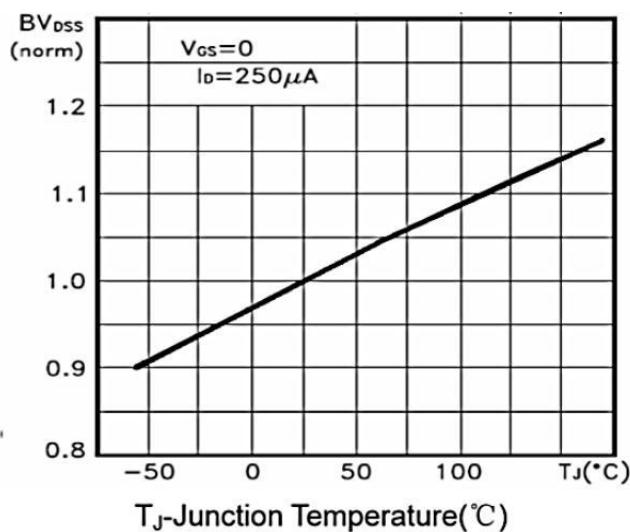


Figure 9 BV<sub>DSS</sub> vs Junction Temperature

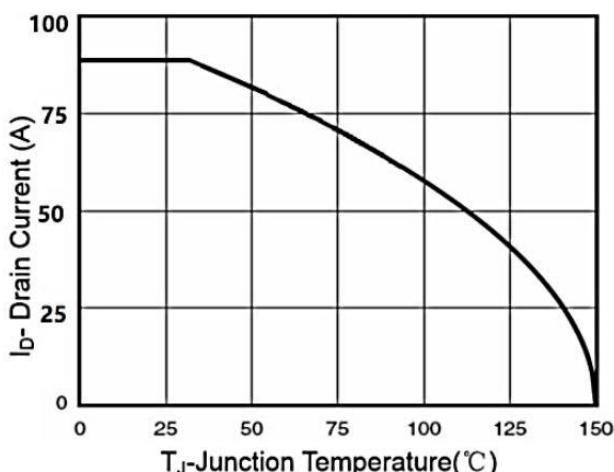


Figure 10 ID Current Derating vs Junction Temperature

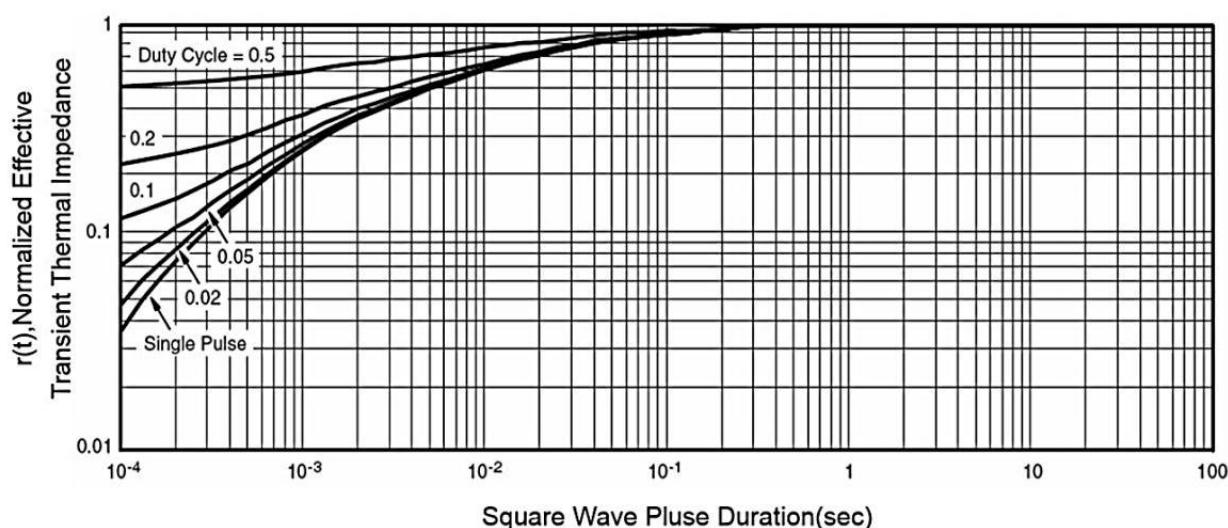
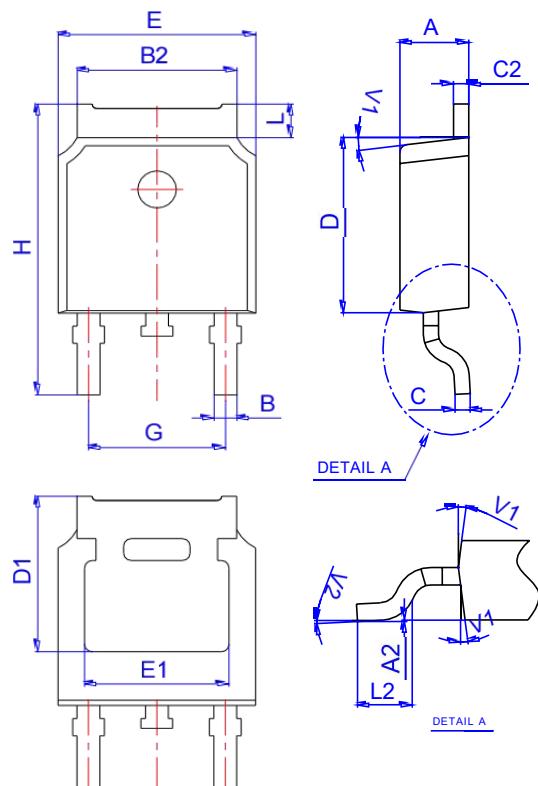


Figure 11 Normalized Maximum Transient Thermal Impedance

## Package Mechanical Data : TO-252-3L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	TO-252-3L		2500